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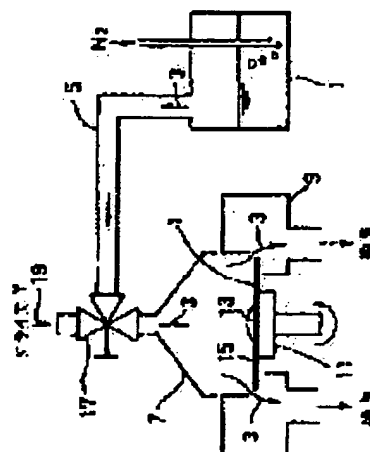
SUGANUMA TATSUMI

**(54) RESIST COATING METHOD**

**(57)Abstract:**

**PURPOSE:** To furnish a resist coating method with which the irregularity in thickness of a resist film can be reduced and concentric circular spots of coating and the like are not generated even when the resist is discharged and applied onto the surface of a rotating wafer in a resist solvent atmosphere.

**CONSTITUTION:** The inside of a coating cup 9, which is covered by a hood 7, is brought into a resist solvent atmosphere, a wafer 15 is rotated by a spin chuck 11 in the above-mentioned resist solvent atmosphere, and resist 13 is spread on the surface of the wafer 15 by centrifugal force. A three-way valve 17 is controlled with the lapse of time of rotation of the wafer 15, dry air 19 is slowly increased on the contrary of vapor 3 while the vapor 3, coming from a vapor generator 1, is being reduced, and sent to the coating cup 9 covered by the hood 7. As a result, the atmosphere around the wafer is changed from a resist solvent atmosphere to a resist dry atmosphere.



## LEGAL STATUS

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